

at least a first conductive pathway from said first surface of said first circuit board to said second surface of said first circuit board to provide access for said at least a first pin of said multi-pin component to at least a first location of said second circuit board; and

at least a second conductive pathway, formed at least partially through said second circuit board, from said first location of said second circuit board to at least a first resistance, wherein said at least a first resistance is associated with said second circuit board.

2. Apparatus, as claimed in Claim 1, wherein said multi-pin component comprises an ASIC.

3. Apparatus, as claimed in Claim 1, wherein said at least a first resistance is positioned on a surface of said second circuit board.

4. Apparatus, as claimed in Claim 1, wherein said at least a first resistance is positioned in an interior region of said second circuit board.

5. Apparatus, as claimed in Claim 1, wherein said at least a first resistance is selected from among a surface mount resistor, a printed resistance and a buried resistance.

6. Apparatus, as claimed in Claim 1, wherein at least a portion of said at least a first conductive pathway comprises a via including a conductive material formed in said first circuit board.

7. Apparatus, as claimed in Claim 1, wherein said second circuit board is wholly aligned within at least a portion of the region defined by said footprint.

8. Apparatus, as claimed in Claim 1, wherein a first portion of said second circuit board is positioned within the region defined by said footprint and a second portion of said second circuit board is positioned within a region outside said footprint.

9. Apparatus, as claimed in Claim 8, wherein said second portion of said second circuit board provides at least a portion of a third conductive pathway to a location of said first circuit board outside said footprint.

10. Apparatus, as claimed in Claim 1, wherein said first pin carries a signal having a frequency greater than about 1 gigahertz.

11. Apparatus, as claimed in Claim 1, wherein each of said first and second circuit boards has a thickness and wherein said at least a first conductive pathway and said at least a second conductive pathway have a combined length which is less than the sum of the thickness of said first and second circuit boards.

12. Apparatus, as claimed in Claim 1, wherein said second circuit board is coupled to said first circuit board by a ball grid array.

13. Apparatus, as claimed in Claim 1, wherein said multi-pin component and said second circuit board are coupled to said main circuit board substantially simultaneously.

Please cancel claim 17 without prejudice or disclaimer of the subject matter recited therein.